

Thermal Conductivity

METALS		(Watts cm °C)
Silver	(Ag)	4.08
Copper	(Cu)	3.94
Gold	(Au)	2.96
Aluminum	(Al)	2.18
Beryllium	(Be)	2.00
Tungsten	(W)	1.74
Rhodium	(Rh)	1.50
Molybdenum	(Mo)	1.46
Brass	(66%Cu, 34% Zn)	1.110
Chromium	(Cr)	0.937
Nickel	(Ni)	0.920
Platinum	(Pt)	0.716
Tin	(Sn)	0.666
Tantalum	(Ta)	0.575
Lead	(Pb)	0.353
Titanium	(Ti)	0.219
Manganese	(Mn)	0.078

INSULATORS		(Watts cm °C)
Diamond	(CVD)	10.0-16.0
Beryllium Oxide 99.5%	(BeO)	2.61
Aluminum Nitride	(AlN)	1.70
Boron Nitride	(HBN 500°)	0.59
Sapphire		0.46
Alumina Oxide 99.6%	(Al ₂ O ₃)	0.36
Alumina Oxide 96%	(Al ₂ O ₃)	0.26
Alumina Oxide 91%	(Al ₂ O ₃)	0.13
Glass		0.015
Mica		0.0043-0.0062
Air		0.00026

BONDING		(Watts cm °C)
Gold Germanium 88/12		0.8834
Gold Tin 80/20		0.6824
Tin Lead Solder (Sn62)		0.4921
Indium 100%		0.2386
Silver Filled Epoxy		0.0156
Epoxy		0.0099

Temperature Conversion

Degrees F	=	9/5 (Degrees C) + 32
Degrees C	=	5/9 (Degrees F) - 32

Gold Conversion

EQUIVALENTS	
1 Kilogram	= 32.15 Troy Ounces
1 Troy Ounce	= 31.103 Grams
1 Pound	= 453.59 Grams
1 Pound	= 14.583 Troy Ounces
24 Karats	= 100% Gold
18 Karats	= 75% Gold
14 Karats	= 58.33% Gold
10 Karats	= 41.66% Gold

Solders

COMPOSITION	MELTING RANGE	
	SOLIDUS	LIQUIDUS
Sn96	221°C	221°C
Sn70	182°C	193°C
Sn63	182°C	182°C
Sn62	176°C	189°C
Sn60	182°C	190°C
Sn50	182°C	215°C
Sn40	182°C	238°C
Sn35	182°C	246°C
Sn30	182°C	254°C
Sn20	182°C	276°C
Sn10	267°C	299°C
Sn5	308°C	312°C
Sb5	232°C	240°C
Pb80	182°C	276°C
Pb70	182°C	254°C
Pb65	182°C	246°C
Ag1.5	309°C	309°C
Ag2.5	304°C	304°C
Ag5.5	304°C	365°C
Gold Germanium (88/12)	356°C	356°C
Gold Tin (80/20)	280°C	280°C
Indium (100%)	157°C	157°C

Material Properties

MATERIAL	ELECTRICAL CONDUCTIVITY (Siemens/m)	
Aluminum	3.538×10 ⁷	
Beryllium	2.256×10 ⁷	
Brass (66%Cu, 34%Zn)	2.564×10 ⁷	(converted from resistivity)
Carbon (graphite)	1.276×10 ⁵	
Chrome	5.104×10 ⁶	
Copper	5.800×10 ⁷	
Gold	4.257×10 ⁷	
Indium	1.392×10 ⁷	
Lead	4.872×10 ⁶	
Nickel	1.462×10 ⁷	
Palladium	9.280×10 ⁶	
Platinum	9.442×10 ⁶	
Rhodium	2.227×10 ⁷	
Silver	6.090×10 ⁷	
Tin	8.700×10 ⁶	
Tin Lead Solder (63/37)	7.284×10 ⁶	(estimated)
Titanium	1.276×10 ⁶	
Titanium Tungsten (TiW)	1.652×10 ⁷	(estimated)
Tungsten	1.821×10 ⁷	

Copper Thickness Conversion

COPPER OUNCES	THICKNESS	
½ Ounce	0.7 Mils	17.78 Microns
1 Ounce	1.4 Mils	35.56 Microns
2 Ounces	2.8 Mils	71.12 Microns
3 Ounces	4.2 Mils	106.68 Microns

Other Conversions

EQUIVALENTS	
1 Micron	= 39.37 Microinches
1 Micron	= 10,000 Angstroms
1 Micron	= 1,000 Nanometers
25.4 Microns	= 1 Mil
1 Angstrom	= 0.003937 Microinches
1 Angstrom	= 0.0001 Microns
10 Angstroms	= 0.03937 Microinches = 1 Nanometer
50 Angstroms	= 0.1968 Microinches = 60/40 Optical
254 Angstroms	= 1 Microinch
100 Nanometers	= 3.937 Microinches
100 Nanometers	= 1,000 Angstroms
1 Nanometer	= 10 Angstroms
1 Microinch	= 254 Angstroms
1 Microinch	= 25.4 Nanometers
39.37 Microinches	= 1 Micron
1 Mil	= 25.4 Microns

TO GET	MULTIPLY	BY
Angstroms	=	Microns x 10,000
Angstroms	=	Microinches x 254
Angstroms	=	Mils x 25,400
Angstroms	=	Nanometers x 10
Microns	=	Nanometers x 0.001
Microns	=	Angstroms x 0.0001
Microns	=	Microinches x 0.0254
Microns	=	Mils x 25.4
Microns	=	Millimeters x 0.01
Nanometers	=	Microns x 1000
Nanometers	=	Mils x 0.03937
Nanometers	=	Microinches x 25.4
Nanometers	=	Angstroms x 0.10
Millimeters	=	Microns x 0.001
Millimeters	=	Mils x 0.0254
Millimeters	=	Microinches x 0.000254
Millimeters	=	Inches x 25.4
Centimeters	=	Inches x 2.54
Centimeters	=	Millimeters x 10
Microinches	=	Microns x 39.37
Microinches	=	Mils x 1000
Microinches	=	Angstroms x 0.003937
Microinches	=	Nanometers x 0.03937
Microinches	=	Millimeters x 39.373
Mils	=	Microns x 0.03937
Mils	=	Microinches x 0.001
Mils	=	Angstroms x 254,000
Mils	=	Millimeters x 39.37
Inches	=	Millimeters x 0.03937
Inches	=	Centimeters x 0.3937
Sq. Inches	=	Sq. Centimeters x 0.15499
Sq. Centimeters	=	Sq. Inches x 6.45
Cu. Inches	=	Cu. Centimeters x 0.06102
Cu. Centimeters	=	Cu. Inches x 16.39
Ounces	=	Grams x 0.03527
Pounds	=	Kilograms x 2.2046
Grams	=	Ounces x 28.349
Kilograms	=	Pounds x 0.4536